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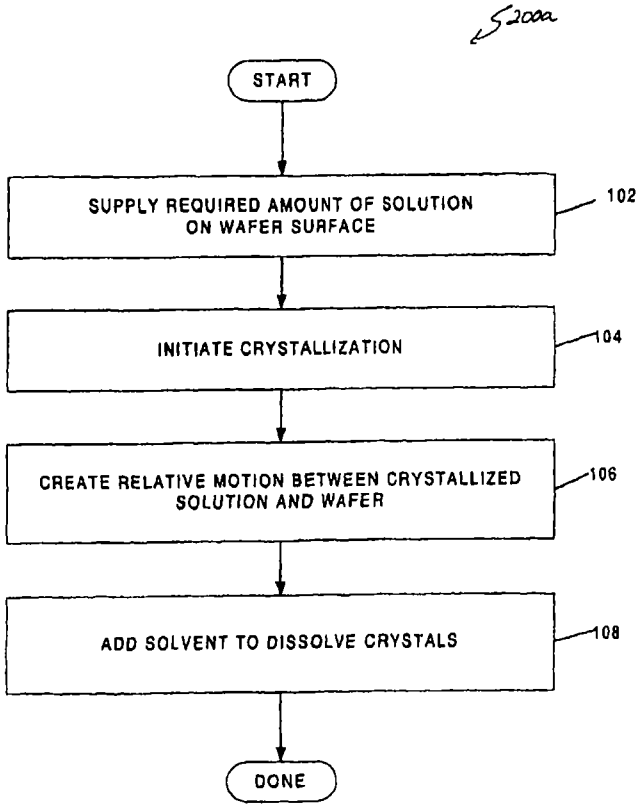
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(54) Title: WAFER CLEANING MODULE AND METHOD FOR CLEANING THE SURFACE OF A SUBSTRATE



(57) Abstract: In a method for cleaning a surface of a substrate an amount of a solution is applied on a surface of the substrate (102). After the solution is applied on the surface, crystallization of the solution is initiated (104) to form a liquid-crystal mixture. Once the liquid-crystal mixture is formed, relative motion between the liquid-crystal mixture and the substrate is created (106) to dislodge contaminants adhered to the substrate. In one alternative metthod, the solution is applied on a pad. In another alternative method, the substrate is place in a bath of the solution. A wafer cleaning module also is described.



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